


<b>AMENDMENT TRANSMITTAL LETTER (Large Entity)</b>					Docket No. FIS920030359US1	
Applicant(s): KAMALESH K. SRIVASTAVA ET AL.						
Application No. 16/708,649	Filing Date 03/17/2004	Examiner P. CAO	Customer No. 29371	Group Art Unit 2814	Confirmation No. 2648	
Invention: METHOD FOR FORMING ROBUST SOLDER INTERCONNECT STRUCTURES BY REDUCING EFFECTS OF SEED LAYER UNDERETCHING						
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COMMISSIONER FOR PATENTS:					AUG 11 2005	
Transmitted herewith is an amendment in the above-identified application.						
The fee has been calculated and is transmitted as shown below.						
CLAIMS AS AMENDED						
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE	
TOTAL CLAIMS	12	20	0	x \$50.00	\$0.00	
INDEP. CLAIMS	3	3	0	x \$200.00	\$0.00	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00	
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00	
<input checked="" type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input checked="" type="checkbox"/> The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account 09-0458 <input checked="" type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input type="checkbox"/> Any patent application processing fees under 37 CFR 1.17. <input type="checkbox"/> Payment by credit card, Form PTO-2038.						
<b>WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.</b>						
 _____ Signature			Dated: August 11, 2005			
Sean F. Sullivan Reg. No. 38,328 Cantor Colburn LLP 55 Griffin Road South Bloomfield, CT 06002 860-286-2929			I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on _____ _____ (Date) _____ Signature of Person Mailing Correspondence _____ Typed or Printed Name of Person Mailing Correspondence			
CC:						

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: KAMALESH K. SRIVASTAVA, ET AL. )  
Serial No.: 10/708,649 ) Group Art Unit: 2814  
Filed: March 17, 2004 )  
For: METHOD FOR FORMING ROBUST )  
SOLDER INTERCONNECT )  
STRUCTURES BY REDUCING EFFECTS ) Confirmation No.: 2648  
OF SEED LAYER UNDERETCHING )

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In response to the Office Action mailed July 12, 2005, please amend the  
Application as follows: